

A 3
optical convergence means for converging each of a plurality of laser beams radiated from each of the laser chips on said optical information medium as the optical spot, and a direction of alignment of said plurality of semiconductor laser chips is substantially perpendicular to said tracking servo direction.

Please cancel claims 11-15 without prejudice or disclaimer of the subject matter thereof.

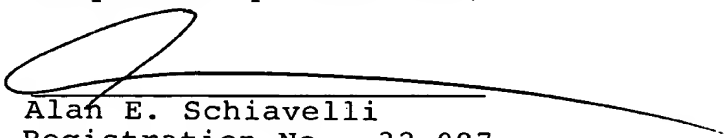
REMARKS

By the above amendment, the specification has been amended, claims 1 and 6 have been amended, and claims 11-15 have been canceled.

Examination of the application and favorable action thereof is respectfully requested.

Please charge any shortage in the fees due in connection with the filing of this paper, to Deposit Account No. 01-2135 (500.40513X00) and please credit any excess fees to such deposit account.

Respectfully submitted,


Alan E. Schiavelli
Registration No. 32,087

AES/MK/cee

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION:

Page 12, after line 20, insert the following paragraphs:

--Other aspects of the present invention include a laser module used for an optical head constituting an optical information recording and reproduction apparatus, which performs tracking servo to record and reproduce the information when an optical spot is radiated on an optical information medium, and including optical convergence means for converging laser beams into the optical spot on the optical information medium, the laser module, comprising a light source where each of semiconductor laser chips having a plurality of wavelengths is mounted on its surface, a photodetecting element for receiving each of a plurality of the laser beams radiated from each of the laser chips, and a package for enclosing the light source and the photodetecting element, wherein the surface where a plurality of the semiconductor laser chips are mounted is substantially perpendicular to the tracking servo direction.

A laser module comprising a semiconductor plate, a mount surface for laser chips provided on the semiconductor plate, a plurality of semiconductor laser chips mounted on the mount surface for the laser chips, a reflection plane provided on the semiconductor plate for reflecting laser beams radiated from a plurality of the semiconductor laser chips, and a photodetecting element, which is provided on the semiconductor

plate, for receiving the laser beams radiated from a plurality of the semiconductor laser chips, wherein the photodetecting elements are arranged at both sides of a plurality of the semiconductor laser chips in a direction where a plurality of the semiconductor laser chips are arranged.

A laser module comprising a package for enclosing the semiconductor plate, wherein the outline of the package in a plane perpendicular to a direction, where the laser beam is radiated from the package, has an approximate rectangular shape in a degree where its long direction and short direction can be distinguished, and a plurality of semiconductor laser chips and the photodetecting element are arranged in a direction of the short side of the package.

A laser module comprising a semiconductor plate, a mount surface for laser chips provided on the semiconductor plate, a plurality of semiconductor laser chips mounted on the mount surface for the laser chips, a reflection plane provided on the semiconductor plate for reflecting laser beams radiated from a plurality of the semiconductor laser chips, and a photodetecting element, which is provided on the semiconductor plate, for receiving the laser beams radiated from a plurality of the semiconductor laser chips, wherein the semiconductor plate includes a plurality of pads for electrically connecting with an external electronic circuit and a plurality of the pads are arranged along a side of the semiconductor plate parallel with a direction where a plurality of the semiconductor laser chips are arranged.

A laser module comprising a plurality of the lead wires

for electrically connecting a package for enclosing the semiconductor plate with an external electronic circuit, wherein the outline of the package in a plane perpendicular to a direction, where the laser beam is radiated from the package, has the approximate rectangular shape in a degree where its long direction and short direction can be distinguished, and a plurality of the lead wires are arranged in a direction of the short side of the package.--

IN THE CLAIMS:

Please amend claims 1 and 6 as follows:

1. (amended) An optical information recording and reproduction apparatus, comprising:

a setting portion of an optical information medium;

a light source where a plurality of semiconductor laser chips are mounted on [a] an identical surface;

optical convergence means for converging each of a plurality of laser beams radiated from each of laser chips into an optical spot on said optical information medium when the optical information medium is set to said setting portion; and

tracking servo means for moving the optical convergence means in a tracking servo direction perpendicular to a track direction such that the optical spot accurately scans the track of the optical information medium,

wherein [the surface on which a plurality of the semiconductor laser chips are mounted] a direction of alignment of said plurality of semiconductor laser chips is

substantially perpendicular to the tracking servo direction.

6. (amended) An optical head used in an optical information recording and reproduction apparatus that performs tracking servo to record and reproduces information when an optical spot is radiated on an optical information medium, wherein the optical head comprises:

a light source on which each of semiconductor laser chips having a plurality of wavelengths is mounted on [a] an identical surface; and

optical convergence means for converging each of a plurality of laser beams radiated from each of the laser chips on said optical information medium as the optical spot, and [the surface where a plurality of the semiconductor laser chips are mounted] a direction of alignment of said plurality of semiconductor laser chips is substantially perpendicular to said tracking servo direction.

Please cancel claims 11-15 without prejudice or disclaimer of the subject matter thereof.